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Fig. 1 shows the DHS (Drop-in Heat Sink) structure of a semiconductor package disclosed in U.S. Patent No. 5,225,710. The package's structure comprises: a die pad 14; a die 12, which is attached to a first surface 141 of the die pad 14 with a suitable adhesive 15, such as a silver paste; a plurality of leads 13 electrically connected to an active surface 121 of the die 12 by a plurality of bonding wires 17, such as gold wires; a heat sink 16 and an encapsulant 11. The die pad 14 and the plurality of leads 13 are all a part of a leadframe and are placed inside an upper mold 18 during manufacture. The heat sink 16 is located inside a lower mold 19, and one surface of the heat sink 16 contacts the bottom of the lower mold 19 with points 161 and 162. Another surface of the heat sink is attached to the second surface 142 and the die pad 14.

Page 3, amend paragraph 4 as follows:

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In use, the known semiconductor packages described above provide heat dissipation paths which extend from the die 12, through the die pad 14, to the heat sinks 16 or 21, and finally to the atmosphere. These heat dissipation paths are too limited because the plurality of leads are not used for dissipating the heat, reducing the efficiency of their heat dissipation.

IN THE CLAIMS

Amend the claims as follows: